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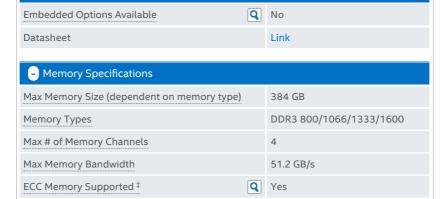
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# Intel® Xeon® Processor E5-2680 (20M Cache, 2.70 GHz, 8.00 GT/s Intel® QPI)

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- Performance		
# of Cores	8	
# of Threads	16	
Processor Base Frequency	2.70 GHz	
Max Turbo Frequency	3.50 GHz	
Cache	20 MB SmartCache	
Bus Speed	8 GT/s QPI	
# of QPI Links	2	
TDP	130 W	
VID Voltage Range	0.60V-1.35V	
Supplemental Information		



Expansion Options	
Scalability	2S Only
PCI Express Revision	3.0
Max # of PCI Express Lanes	40

Package Specifications	
Sockets Supported	FCLGA2011
Max CPU Configuration	2
T <sub>CASE</sub>	85°C
Package Size	52.5mm x 45.0mm
Low Halogen Options Available	See MDDS

**Technologies** 

Intel® Xeon® Processor E5 Family

Intel® Xeon® Processor E5-2600 Product Family

Products formerly Sandy Bridge EP

#### **Quick Links**

Export Full Specifications > Support Overview >

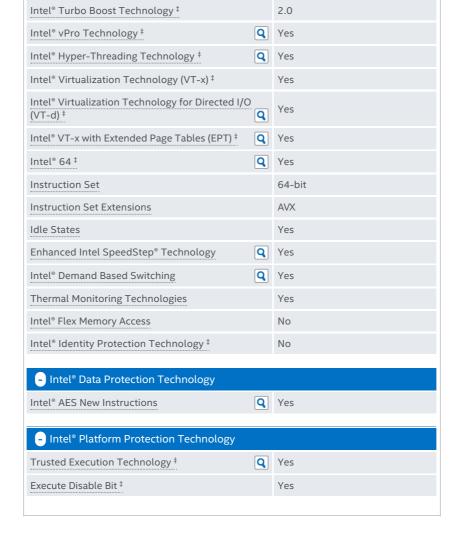
### **PCN/MDDS Information**

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## **SROKH**

919064: PCN | MDDS 919846: PCN | MDDS SROGY

917883: PCN | MDDS



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Refer to Datasheet for formal definitions of product properties and features

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i5-2430M/i5-2430M/i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer -unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

 $Intel \ processor \ numbers \ are \ not \ a \ measure \ of \ performance. \ Processor \ numbers \ differentiate \ features \ within \ each \ processor \ family, \ not \ across \ different \ processor \ families. \ See \ http://www.intel.com/content/www/us/en/processors/processor-numbers.html \ for \ details.$ 

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Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.





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